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**Itakura et al.**

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- (54) **SEMICONDUCTOR PACKAGE**
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- (52) **U.S. Cl.**  
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- (58) **Field of Classification Search**  
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CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;  
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See application file for complete search history.

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PC

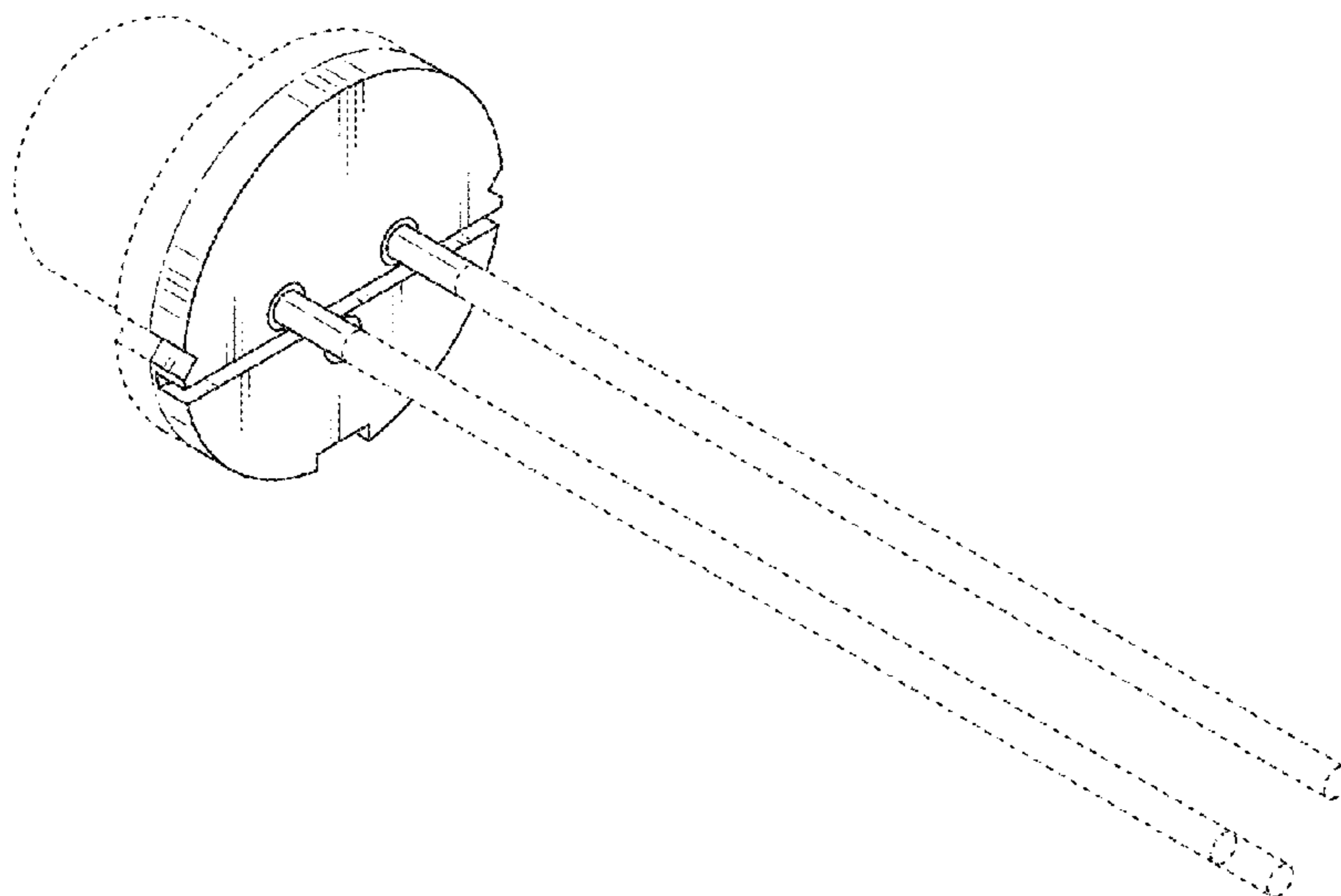
(57) **CLAIM**

The ornamental design for a semiconductor package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and left side perspective view of a semiconductor package showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a top view thereof;  
FIG. 5 is a bottom view thereof;  
FIG. 6 is a left side view thereof; the right side view being a mirror image thereof;  
FIG. 7 is a cross sectional view taken along line 7-7 of FIG. 2, with the internal system omitted; and,  
FIG. 8 is another perspective view thereof, showing the state in use.  
The parts shown in even dashed broken lines do not form part of the claimed design.

**1 Claim, 5 Drawing Sheets**



(56)

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Fig. 1

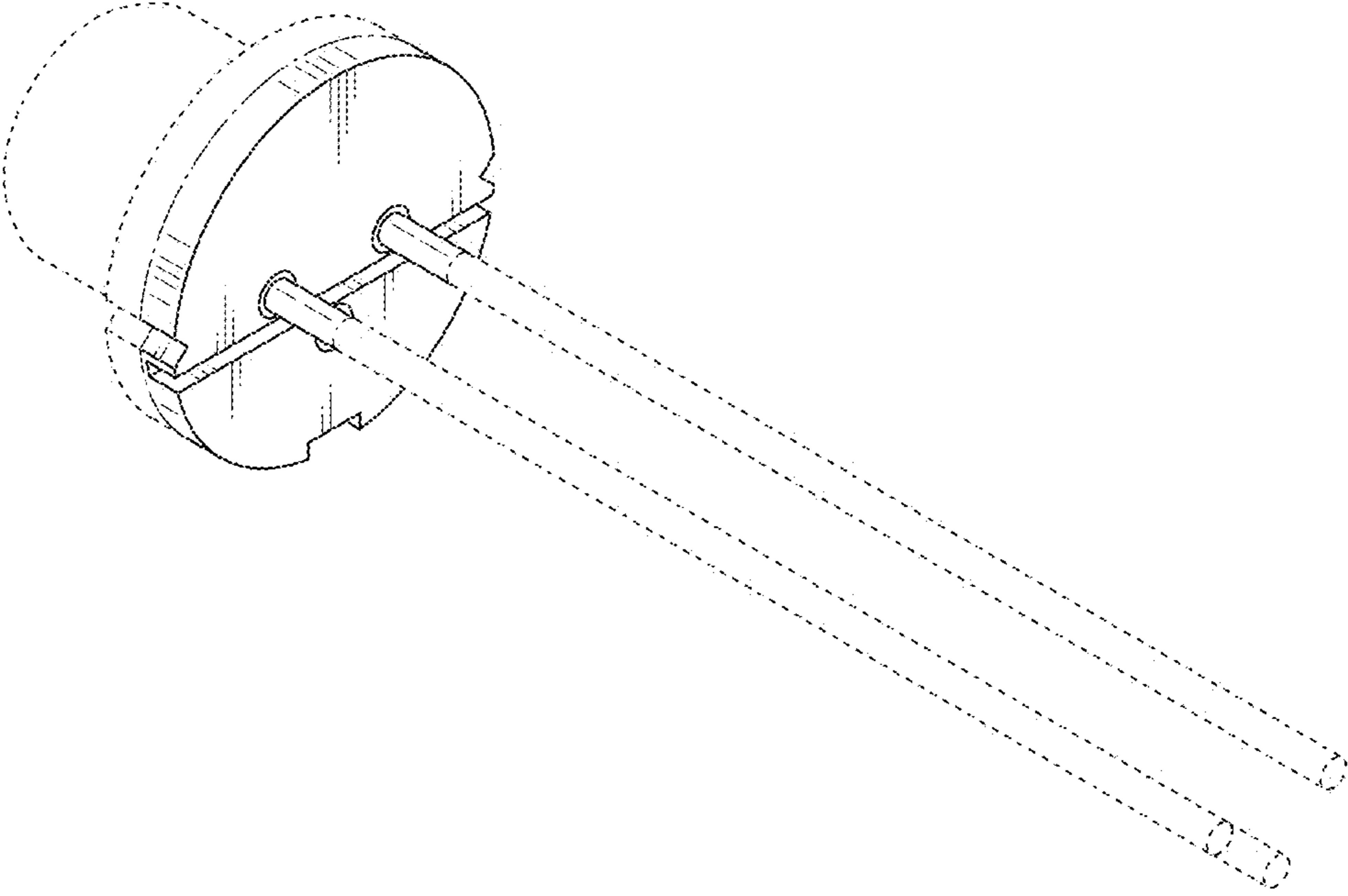


Fig. 2

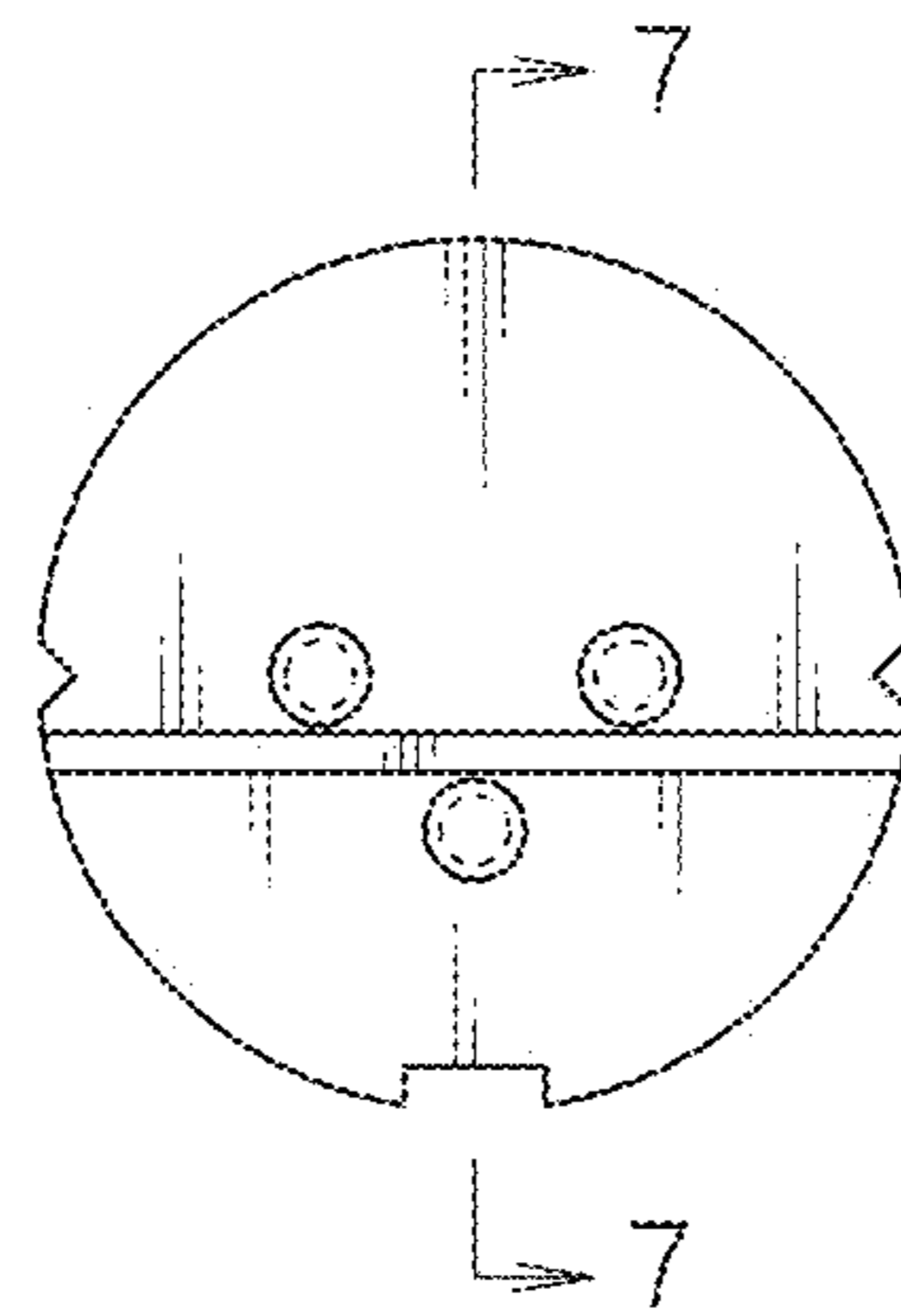


Fig. 3

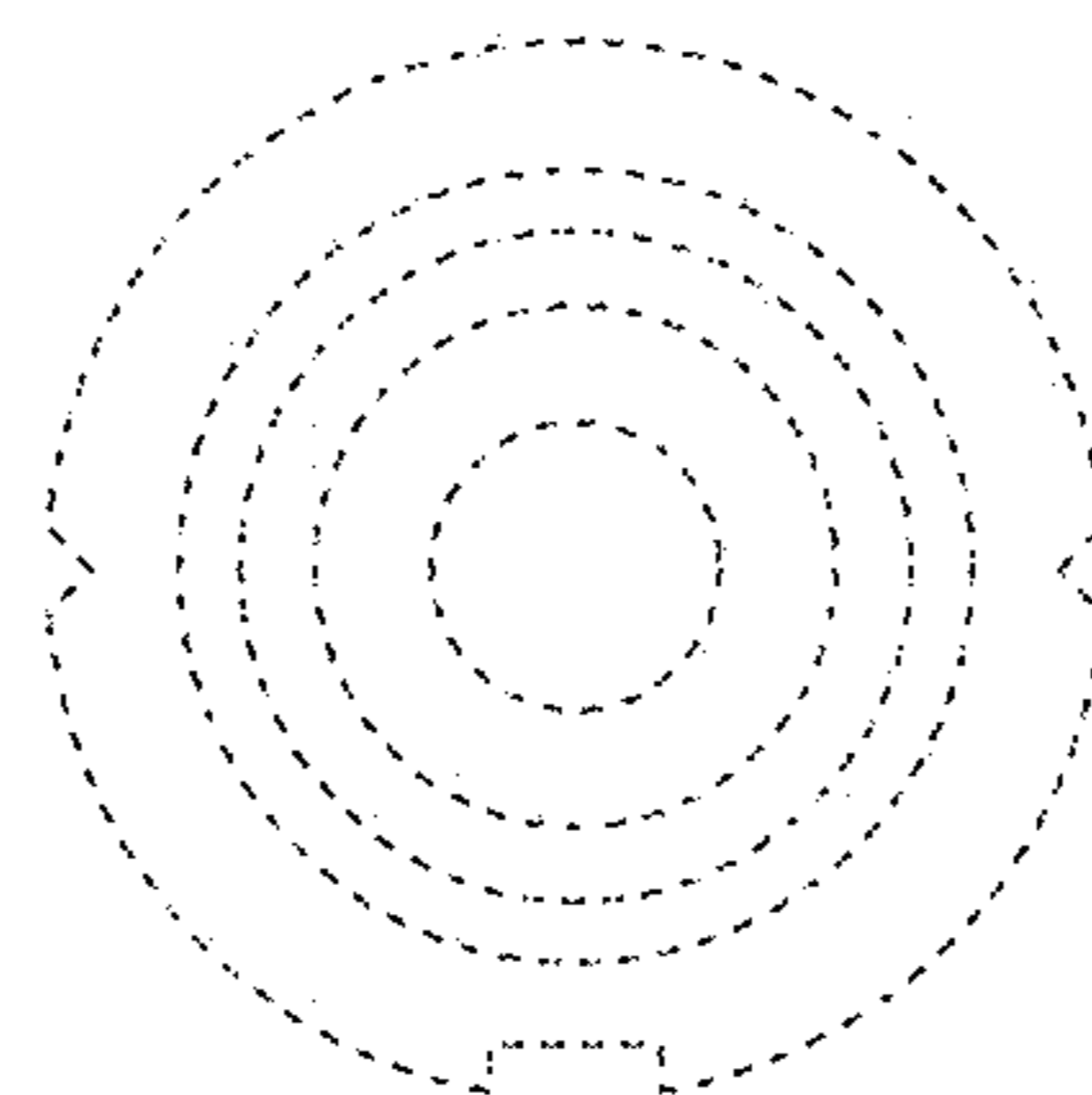


Fig. 4

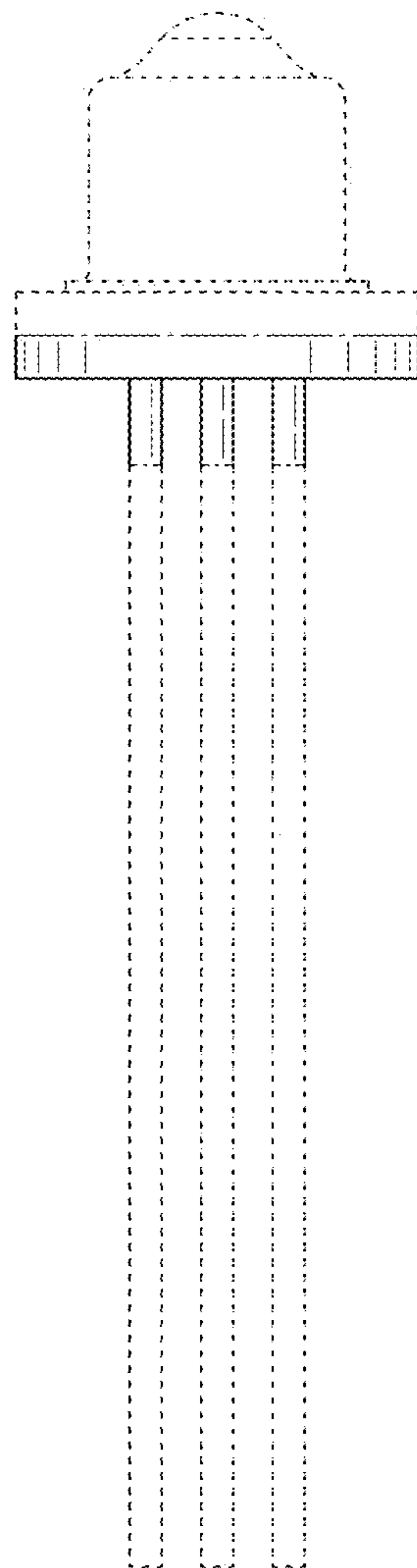


Fig. 5

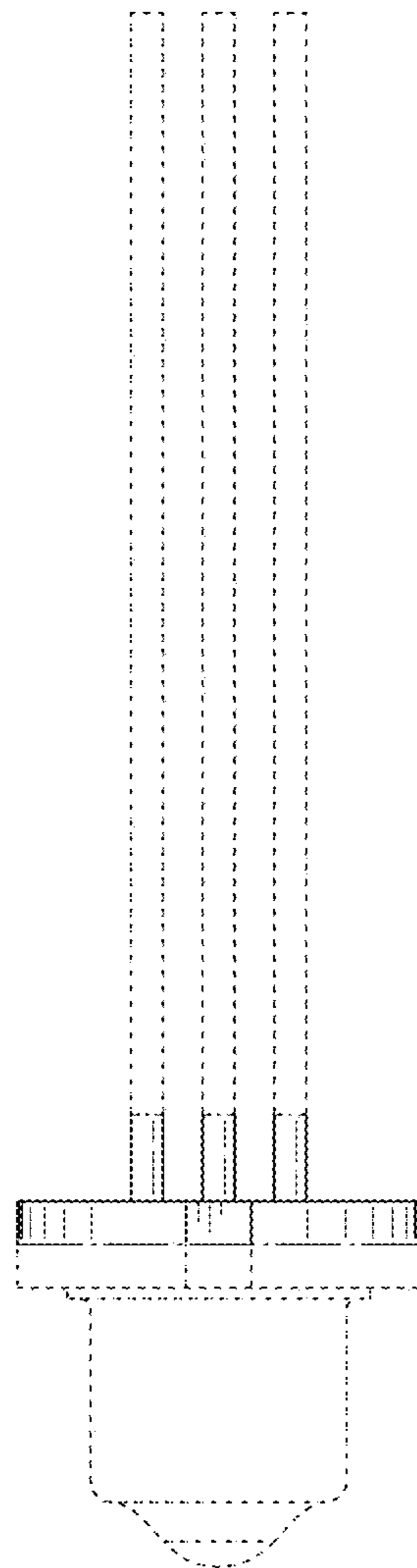


Fig. 6

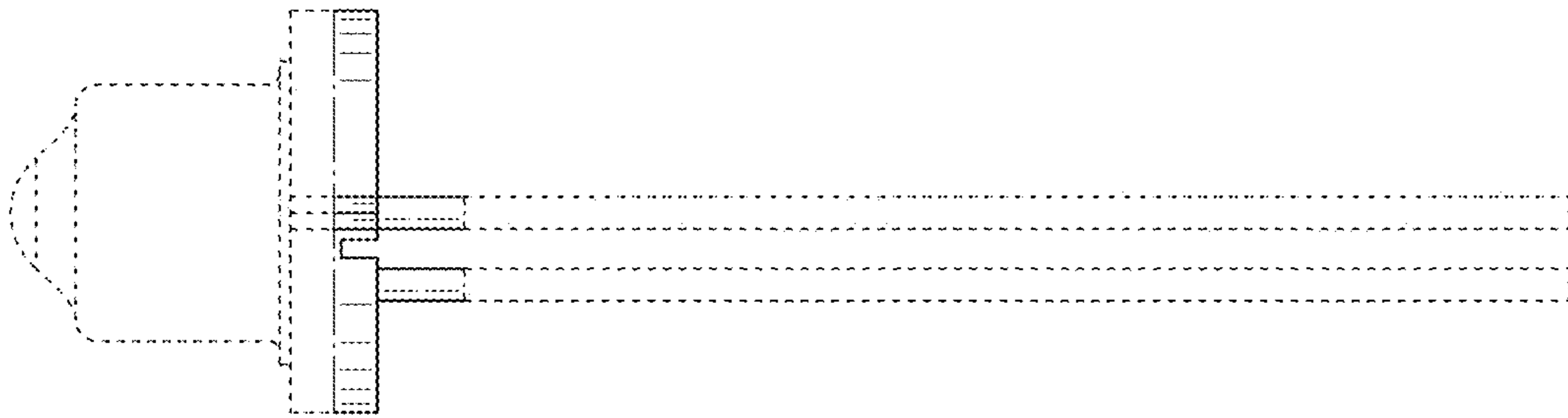


Fig. 7

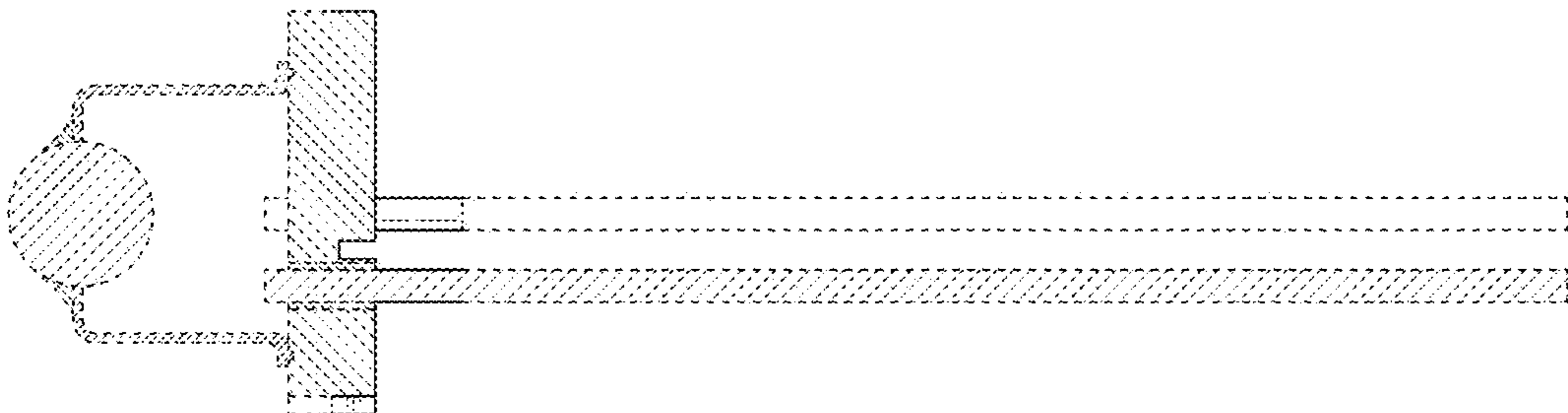


Fig. 8

